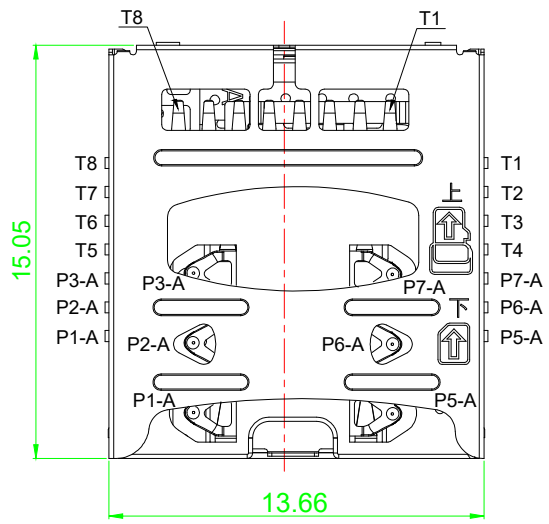
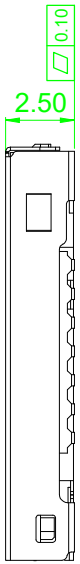
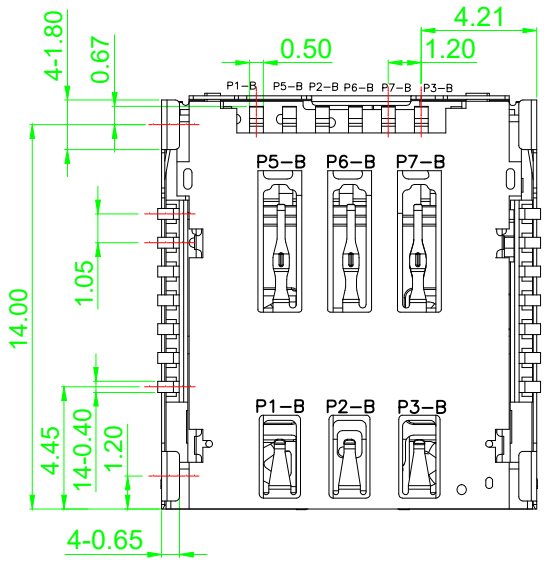
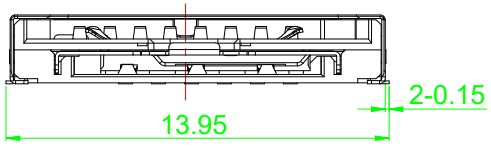
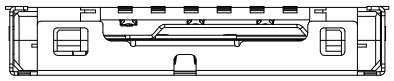
| Rev. | Description. | Date | App. |
|---|---|---|---|
| 01 | | | |

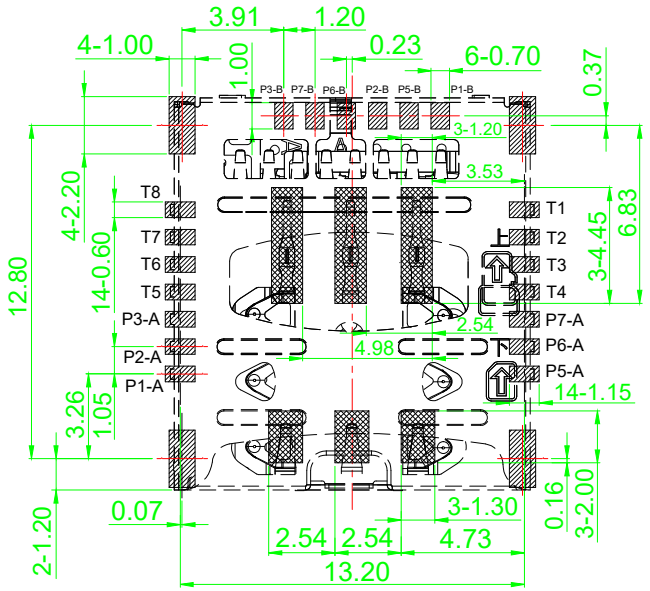





RECOMMENDED PCB LAYOUT(TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12mm

PAD AREA  NO CIRCUIT AREA (TOP VIEW)

NOTES:
1.MATERIAL:
HOUSING: LCP, UL94V-0, WHITE
CONTACT: PHOSPHOR BRONZE
SHELL: SUS304

2.FINISH:
CONTACT:
CONTACT AREA: G/F GOLD PLATED
SOLDER AREA: G/F GOLD PLATED
UNDER PLATING: NICKEL PLATED
SHELL:
SOLDER AREA: G/F GOLD PLATED
UNDER PLATING: NICKEL PLATED

3.SPECIFICATION:
CURRENT RATING: 0.5A / (1PIN)
DIELECTRIC WITHSTANDING: 250V AC FOR 1 MINUTE
CONTACT RESISTANCE: 60mΩ MAX.
INSULATION RESISTANCE: 1000MΩ MIN.
OPERATING TEMPERATURE: -25°C ~ +70°C
DURABILITY: 3000 CYCLES MIN.
INSERTION FORCE: 20N MAX.
WITHDRAWAL FORCE: 1N

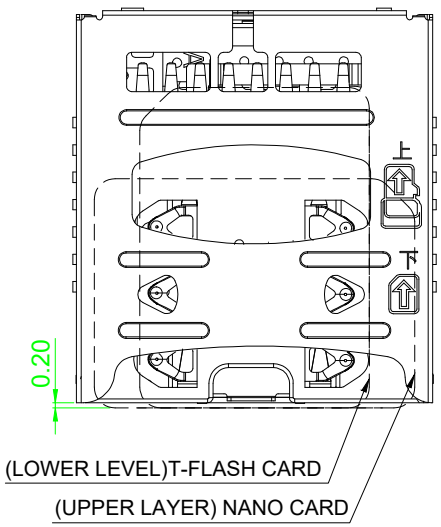
| T-CARD P/N | NAME |
|---|---|
| T1 | DAT2 |
| T2 | CD/DAT3 |
| T3 | CMD |
| T4 | VDD |
| T5 | CLK |
| T6 | VSS |
| T7 | DAT0 |
| T8 | DAT1 |

| NANO SIM P/N | NAME |
|---|---|
| P1 A/B | VCC |
| P2 A/B | RST |
| P3 A/B | CLK |
| P5 A/B | GND |
| P6 A/B | VPP |
| P7 A/B | I/O |

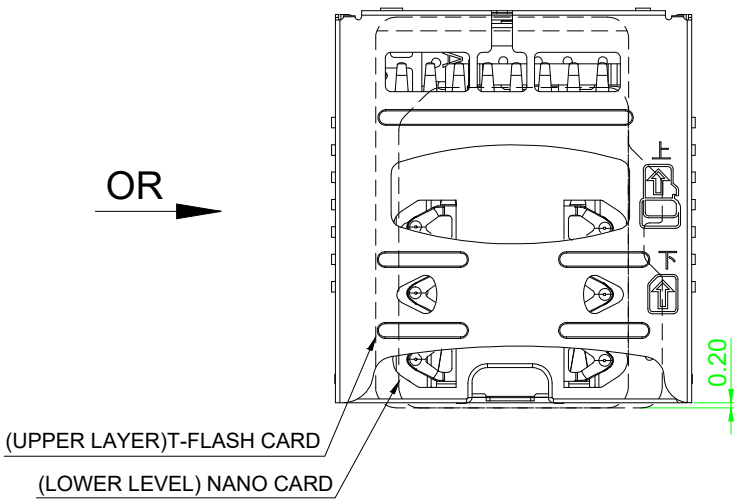
研騰國際企業股份有限公司
YANNIS ELECTRONICS CO.,LTD.

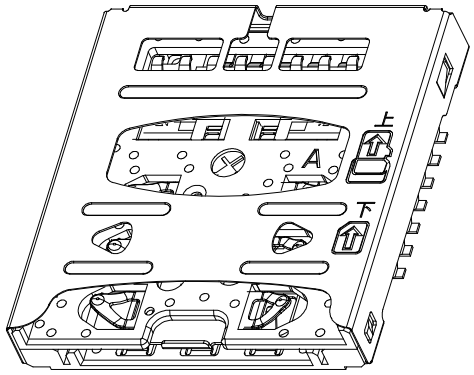
| | | | | | | | | |
|---|---|---|---|---|---|---|---|---|
| PROJECTION: | UNIT: mm | GENERAL TOLERANCES: .X ±0.30 X°. ± 3° .XX ±0.20 .X° ± 1° .XXX ±0.10 | APPROVED | David | SHEET: 1 OF 3 | REV.: A | NAME | Micro SD + Nano SIM Combo Type H:2.5mm |
| | SCALE: Free | | CHECKED | Sunny | | | | |
| | | | DRAWN | Juno | DATE: 2021/01/14 | | PART NO. | MSD-0116000 DWG NO. MSD-0116000_01 |

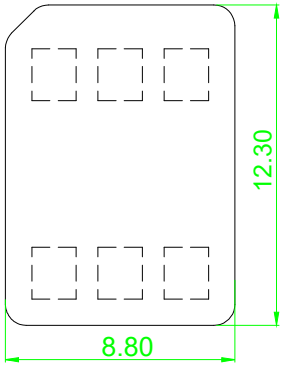
| Rev. | Description. | Date | App. |
|---|---|---|---|
| 01 | | | |



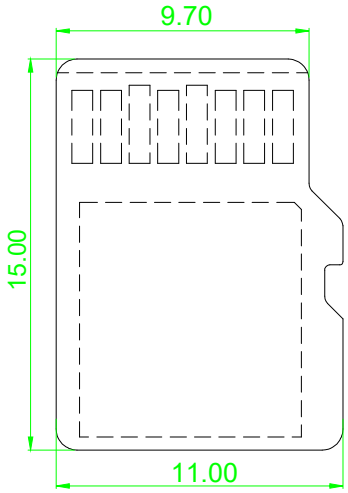

OR



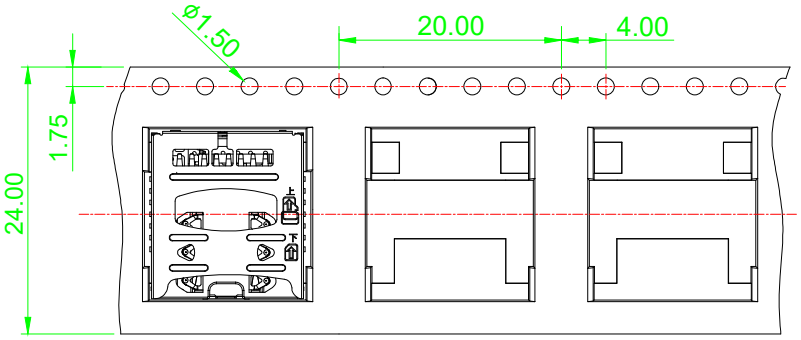

NANO SIM CARD




T-FLASH CARD

| | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| 研騰國際企業股份有限公司<br>YANNIS ELECTRONICS CO.,LTD. | PROJECTION: | UNIT: mm<br>SCALE: Free | GENERAL TOLERANCES:<br>.X ±0.30 X°. ± 3°<br>.XX ±0.20 .X° ± 1°<br>.XXX ±0.10 | APPROVED | David | SHEET: 2 OF 3 | REV.: A | NAME | Micro SD + Nano SIM Combo Type H:2.5mm | |
| | | | | CHECKED | Sunny | | | | | |
| | | | | DRAWN | Juno | DATE: 2021/02/02 | | PART NO. | MSD-0116000 | DWG NO. MSD-0116000_01 |

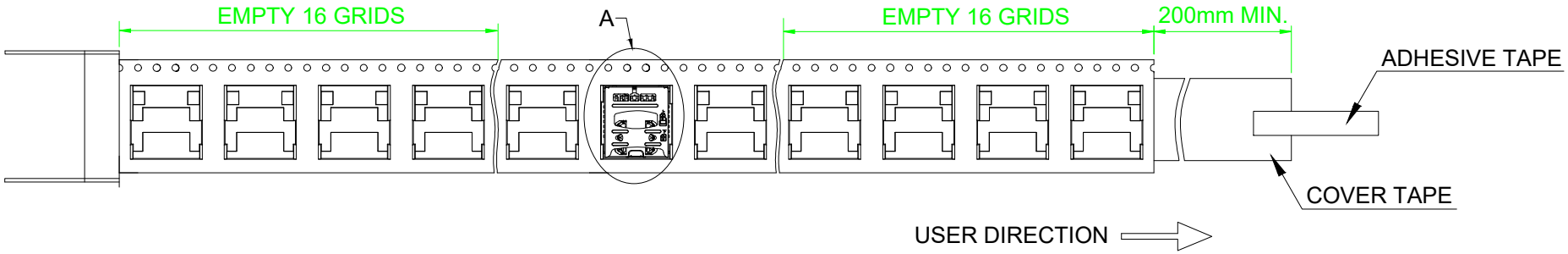
| Rev. | Description. | Date | App. |
|---|---|---|---|
| 01 | | | |

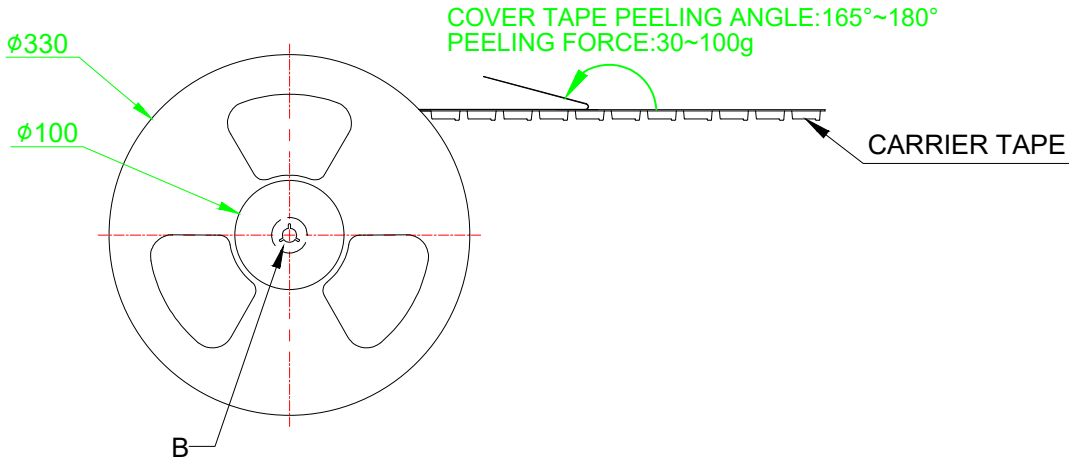


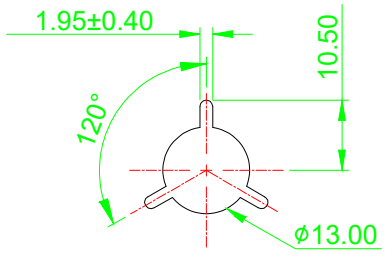

DETAIL A (SCALE: 2:1)

NOTES:

1.PACKING: 1,000 PCS/REEL
12,000 PCS/OUTER CARTON
2.MATERIAL: CARRIER TAPE: PS BLACK
COVER TAPE: PET FILM
REEL: PLASTIC
3.PEEL STRENGTH OF COVER TAPE:
30~100g(PEEL SPEED 300mm/MINUTE)




DETAIL B

| | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| 研騰國際企業股份有限公司<br>YANNIS ELECTRONICS CO.,LTD. | PROJECTION: | UNIT: mm<br>SCALE: Free | GENERAL TOLERANCES:<br>.X ±0.30 X°. ± 3°<br>.XX ±0.20 .X° ± 1°<br>.XXX ±0.10 | APPROVED | David | SHEET: 3 OF 3 | REV.: A | NAME | Micro SD + Nano SIM Combo Type H:2.5mm Packing |
| | | | | CHECKED | Sunny | | | | |
| | | | | DRAWN | Juno | DATE: 2021/02/02 | | PART NO. | MSD-0116000 DWG NO. MSD-0116000_01 |